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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR:	Edmund D. Blackshear)	EXAMINER:	A. O. Williams
)		
SERIAL NO.:	10/719,334)	ART UNIT:	2826
)		
FILING DATE:	November 21, 2003)	DATE:	May 11, 2006
)		
FOR:	OVERLAP STACKING OF CENTER BUS BONDED MEMORY CHIPS FOR DOUBLE DENSITY AND METHOD OF MANUFACTURING THE SAME			

AMENDMENT UNDER RULE 312

MAIL STOP ISSUE FEE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Notice of Allowance dated **March 13, 2006**, please amend the application as follows: